## **Surface Mount Schottky Barrier Diode**

Forward Current - 0.2 A Reverse Voltage - 30 V

#### **Description**

- Low Forward Voltage
- High Current Capability
- Fast Switching Speed
- Surface Mound Device Type

#### **Mechanical Data**

- ●Case: SOT23 Package
- ◆Case Material: "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Terminals:Matte tin plated,solderable per MIL-STD-750 .method 2026
- Component in accordance to RoHS
- Halogen Free

Note: Products with logo Are made by HY Electronic (Cayman) Limited.

### **Ordering Information**

• Package :SOT23

• Reel Size :7 (inches)

• Quantity Per Reel :3,000/Tape & Reel

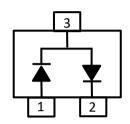
• Quantity One Box :45,000/Tape & Reel

## **Package Outline**

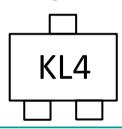


SOT23 Top View

## **Device Schematic & PIN Configuration**



## **Product Type Marking Code**



#### Maximum Ratings (@TA = +25°C, unless otherwise specified.)

#### Absolute Ratings

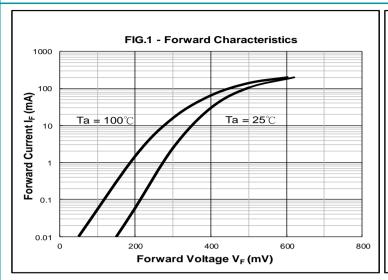
Parameter	Symbol	Value	Unit			
Repetitive Peak Reverse Voltage	Vrrm	30	V			
Forward Rectified Current	Iғм	200	mA			
Peak Forward Surge Current @ t = 8.3ms	lгsм	600	mA			
Power Dissipation	Po	200	mW			
Storage Temperature Range	Тѕтс	-50 to +150	° C			
Thermal Resistance from Junction to Ambient	RөJA	500	° C/W			
Junction Temperature	Tu	125	° C			

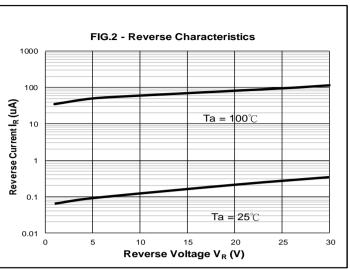
#### **Electrical Characteristics**

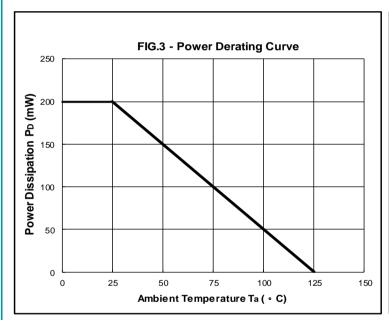
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Reverse Voltage	Ir=100uA	V <sub>BR</sub>	30	-	-	V
Reverse Current	VR=25V	<b>I</b> R	-	-	2	uA
Forward Voltage	I=0.1mA		-	-	0.24	
	I==1mA	VF	-	-	0.32	V
	IF=10mA		-	-	0.40	
	I=30mA		-	-	0.50	
	I=100mA		-	-	1.00	
Junction Capacitance	VR = 1V, F = 1MHz	Cı	-	-	10	pF
Reverse Recovery time	IF=IR=10mA Irr=0.1xIR · RL=100Ω	T <sub>RR</sub>	-	-	5	ns

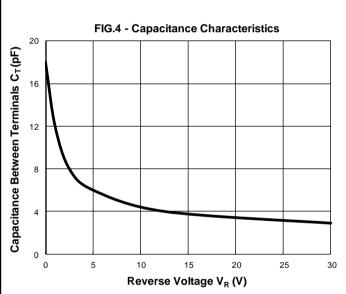
BAT54S-7-99-01-BC1589

# **Rating and Characteristic Curves**



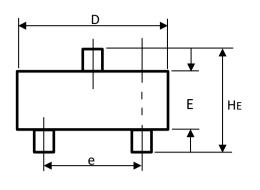


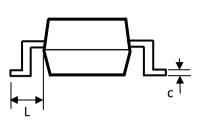




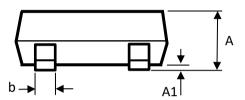


# **Package Outline Dimensions**

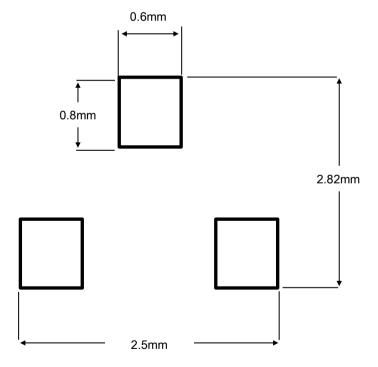




SOT23 Package					
Dim	Min	Max			
Α	0.90	1.15			
A1	0.00	0.10			
b	0.30	0.50			
С	0.08	0.15			
D	2.80	3.00			
Е	1.20	1.40			
е	1.80	2.00			
L	0.55 REF				
HE	2.25	2.55			
All Dimensions in mm					



# **Suggested Soldering Pad Layout**



#### Note:

- 1. The pad layout is for reference purposes only.
- 2.General tolerance ±0.05mm

# **Legal Disclaimer Notice**

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